

General Description

SFGMOS[®] MOSFET is based on Oriental Semiconductor's unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The low V_{th} series is specially designed to use in synchronous rectification power systems with low driving voltage.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery



Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

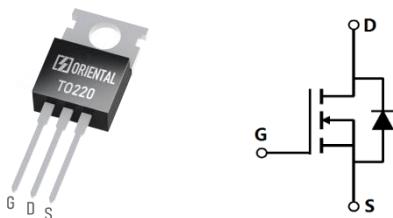
Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_j(max)$	120	V
$I_D, pulse$	180	A
$R_{DS(ON), max} @ V_{GS}=10V$	13	mΩ
Q_g	39.6	nC

Marking Information

Product Name	Package	Marking
SFG60N12PF	TO220	SFG60N12P

Package & Pin information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	120	V
Gate source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	60	A
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	180	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	60	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S,\text{pulse}}$	180	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	140	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	100	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.89	$^\circ\text{C}/\text{W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	120			V	$V_{GS}=0 \text{ V}, I_D=250 \mu\text{A}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.5		2.5	V	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		10.6	13	$\text{m}\Omega$	$V_{GS}=10 \text{ V}, I_D=30 \text{ A}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=20 \text{ V}$
				-100		$V_{GS}=-20 \text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=120 \text{ V}, V_{GS}=0 \text{ V}$
Gate resistance	R_G		3.4		Ω	$f=1 \text{ MHz}, \text{Open drain}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		2810		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 kHz
Output capacitance	C _{oss}		356		pF	
Reverse transfer capacitance	C _{rss}		8.3		pF	
Turn-on delay time	t _{d(on)}		20.4		ns	V _{GS} =10 V, V _{DS} =50 V, R _G =2 Ω, I _D =25 A
Rise time	t _r		5.7		ns	
Turn-off delay time	t _{d(off)}		45.1		ns	
Fall time	t _f		6.3		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		39.6		nC	V _{GS} =10 V, V _{DS} =50 V, I _D =25 A
Gate-source charge	Q _{gs}		6.8		nC	
Gate-drain charge	Q _{gd}		8.0		nC	
Gate plateau voltage	V _{plateau}		3.5		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =60 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		79.5		ns	V _R =50 V, I _S =25 A, di/dt=100 A/μs
Reverse recovery charge	Q _{rr}		210		nC	
Peak reverse recovery current	I _{rrm}		4.4		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=50 V, V_{GS}=10 V, L=0.3 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

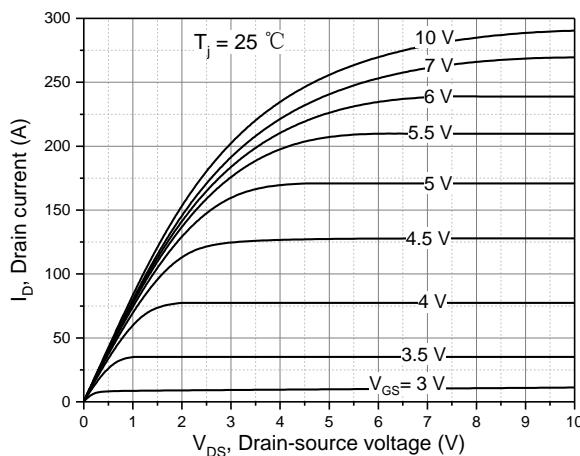


Figure 1. Typ. output characteristics

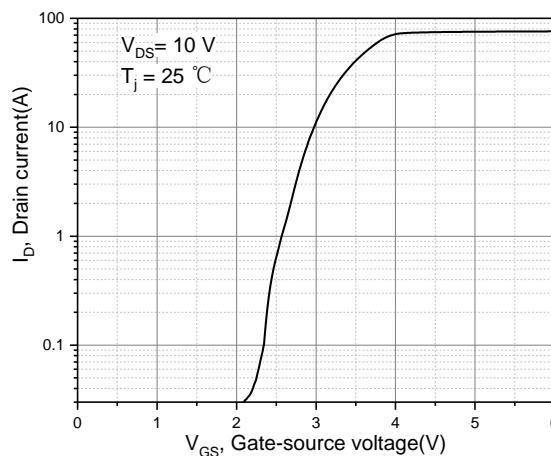


Figure 2. Typ. transfer characteristics

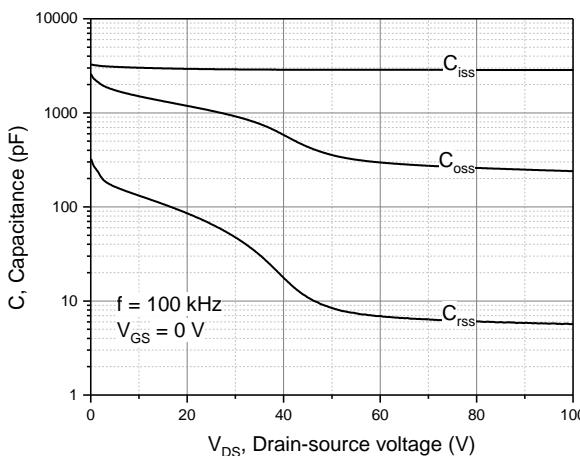


Figure 3. Typ. capacitances

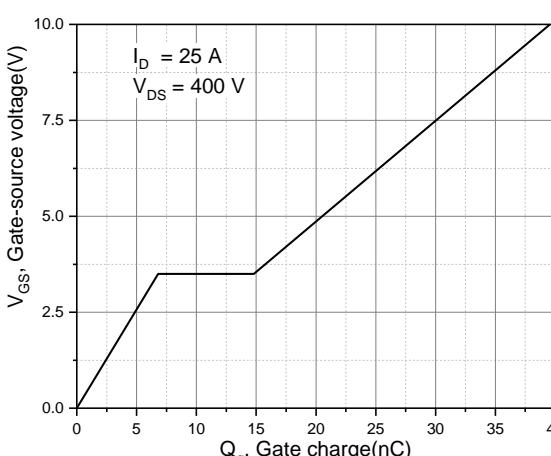


Figure 4. Typ. gate charge

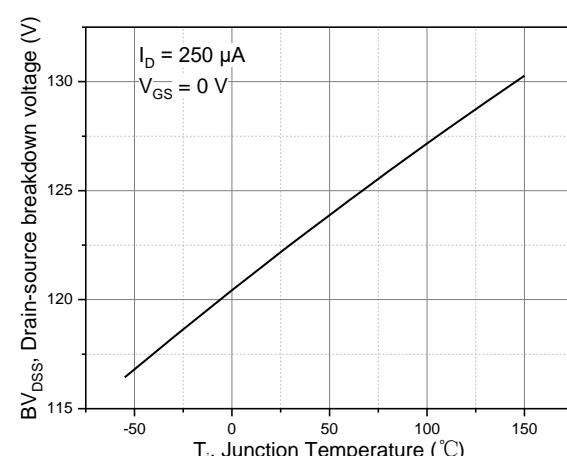


Figure 5. Drain-source breakdown voltage

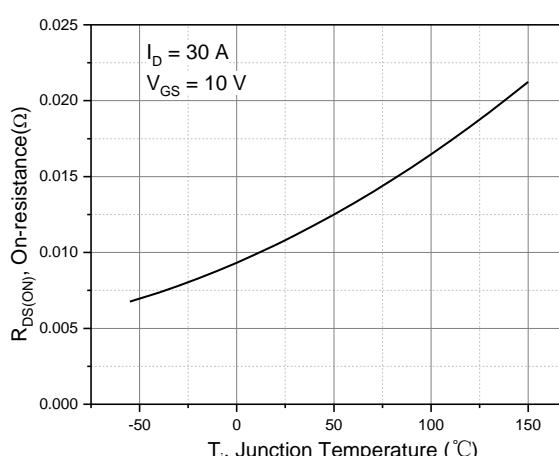


Figure 6. Drain-source on-state resistance

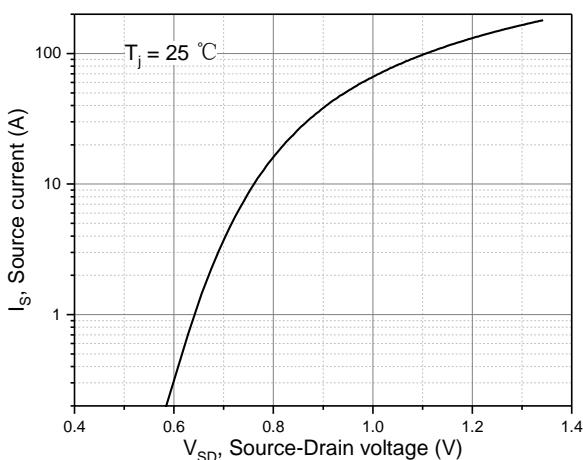


Figure 7. Forward characteristic of body diode

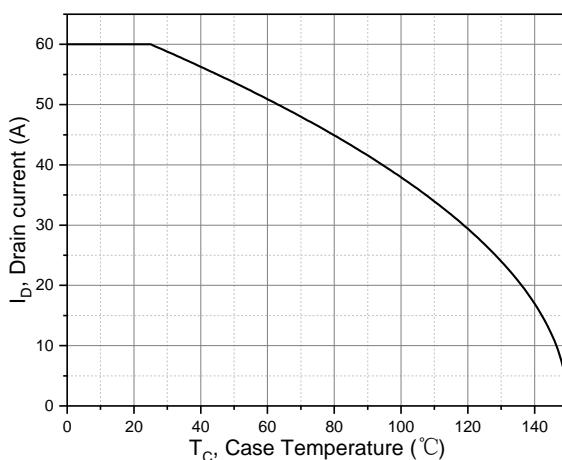


Figure 8. Drain current

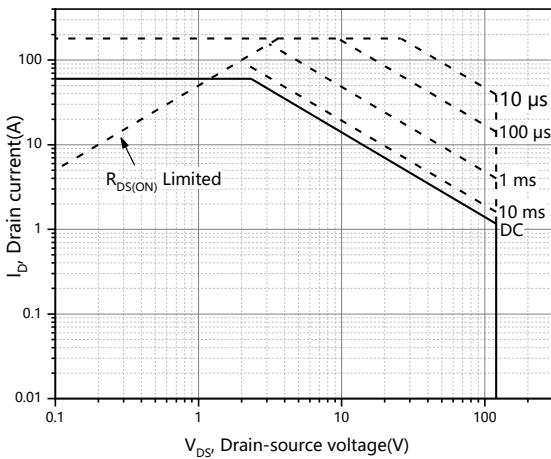


Figure 9. Safe operation area T_C=25 °C

Test circuits and waveforms

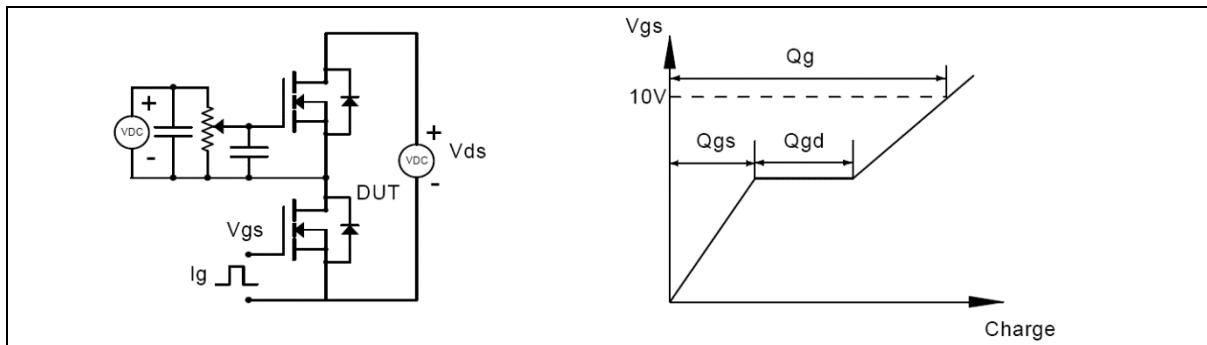


Figure 1. Gate charge test circuit & waveform



Figure 2. Switching time test circuit & waveforms



Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

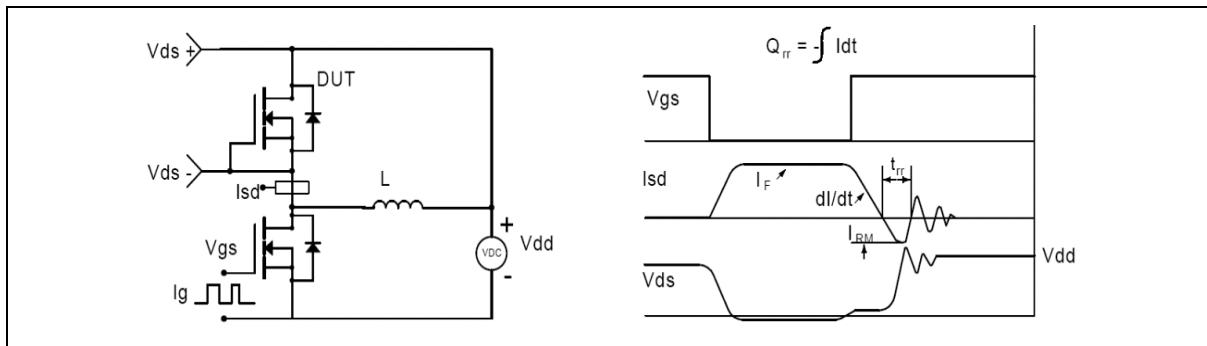
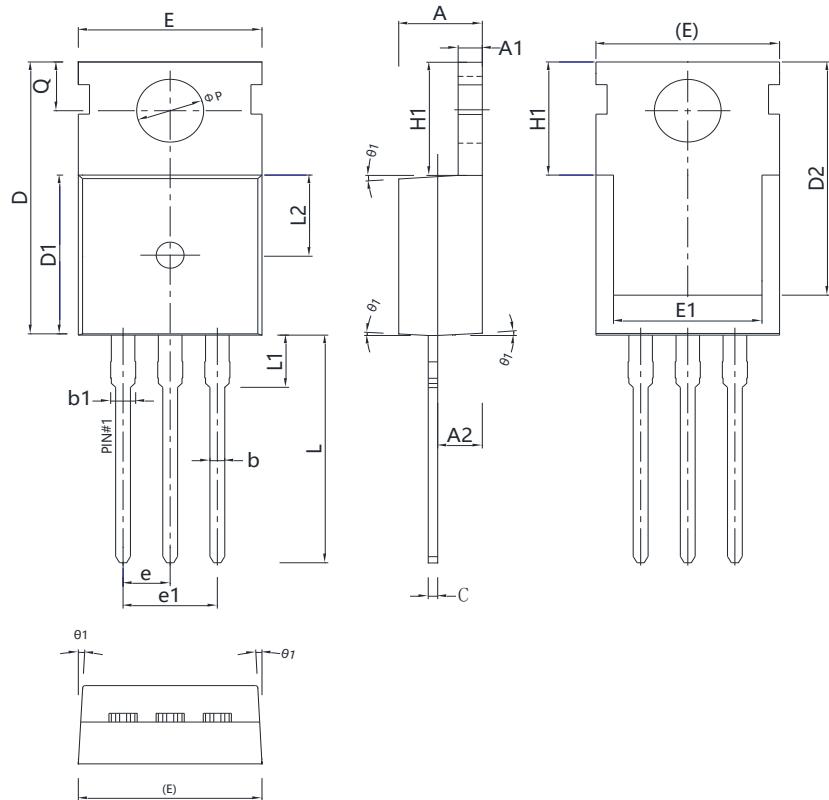


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	4.40	4.50	4.60
A1	1.27	1.30	1.33
A2	2.30	2.40	2.50
b	0.70	-	0.90
b1	1.27	-	1.40
c	0.45	0.50	0.60
D	15.30	15.70	16.10
D1	9.10	9.20	9.30
D2	13.10	-	13.70
E	9.70	9.90	10.20
E1	7.80	8.00	8.20
e	2.54 BSC		
e1	5.08 BSC		
H1	6.30	6.50	6.70
L	12.78	13.08	13.38
L1	-	-	3.50
L2	4.60 REF		
ΦP	3.55	3.60	3.65
Q	2.73	-	2.87
θ1	1°	3°	5°

Version 1: TO220-J package outline dimension

Ordering Information

Package Type	Units/Tube	Tubes / Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO220-J	50	20	1000	5	5000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFG60N12PF	TO220	yes	yes	yes

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